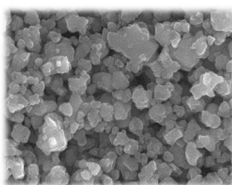


## Semiconductor Module Peripheral Materials

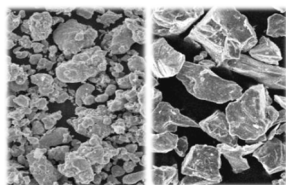
TODA KOGYO Group supports high functionality of semiconductor module peripheral devices with the raw materials. Our cutting edge materials and technologies contribute to the expansion of the semiconductor industry.

### Inductor (Raw material powder)

Soft ferrite  
[FRX series]



Soft magnetic metal



(Fe-Si-Cr, Fe-Si-Al)

### Inductor (Material for module)

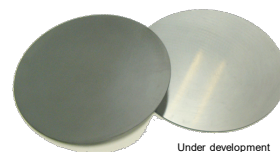
Epoxy-based  
magnetic adhesive



Under development

(Increase of inductance in component)

Wafer-shaped ferrite plate

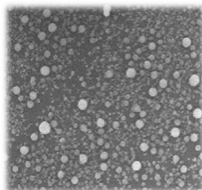


Under development

(Substrate for module formation  
in semiconductor process)

### Encapsulant (Chlorine capture)

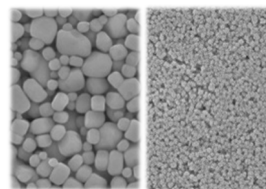
Layered double hydroxide  
(Hydrotalcite)



(Fine particle type)

### Multilayer ceramic capacitor

Barium titanate



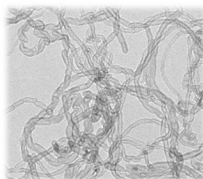
(For dielectric layer or filler  
in electrode layer)



Dispersion product

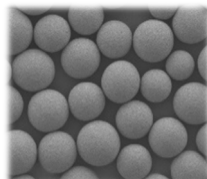
### Thermal conductive material/technology

Carbon nanotube



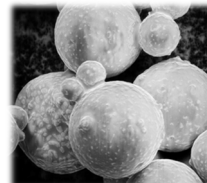
Under development

Spherical composite particle  
granulation technology



### Noise suppression material/sheet

Spherical soft ferrite  
granular particle



Under development

Flexible ferrite sheet/tape

